

INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(51) International Patent Classification ⁶: B32B 27/32, B44C 1/16	A1	(11) International Publication Number: WO 98/55296 (43) International Publication Date: 10 December 1998 (10.12.98)
(21) International Application Number: PCT/US97/18295 (22) International Filing Date: 13 October 1997 (13.10.97) (30) Priority Data: 08/867,891 3 June 1997 (03.06.97) US (71) Applicant: MINNESOTA MINING AND MANUFACTURING COMPANY [US/US]; 3M Center, P.O. Box 33427, Saint Paul, MN 55133-3427 (US). (72) Inventors: EMSLANDER, Jeffrey, O.; P.O. Box 33427, Saint Paul, MN 55133-3427 (US). REGNIER, Diane, L.; P.O. Box 33427, Saint Paul, MN 55133-3427 (US). FLEMING, Danny, L.; P.O. Box 33427, Saint Paul, MN 55133-3427 (US). (74) Agents: HORNICKEK, John, H. et al.; Minnesota Mining and Manufacturing Company, Office of Intellectual Property Counsel, P.O. Box 33427, Saint Paul, MN 55133-3427 (US).		(81) Designated States: AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CU, CZ, DE, DK, EE, ES, FI, GB, GE, GH, HU, ID, IL, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, UA, UG, UZ, VN, YU, ZW, ARIPO patent (GH, KE, LS, MW, SD, SZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, ML, MR, NE, SN, TD, TG). Published <i>With international search report.</i>
(54) Title: MULTILAYER ELECTRONIC CUTTER FILM FOR IMAGE GRAPHICS (57) Abstract A multilayer polyolefin film for use as an electronic cutter film is disclosed. The film provides improved abrasion and graffiti resistance, and adhesive anchorage versus a comparable single layer film while still maintaining excellent cutting properties. The film also shows excellent resistance to "surface impressions", which are a major problem for traditional vinyl-containing electronic cutting films.		